



Sierra Components, Inc.

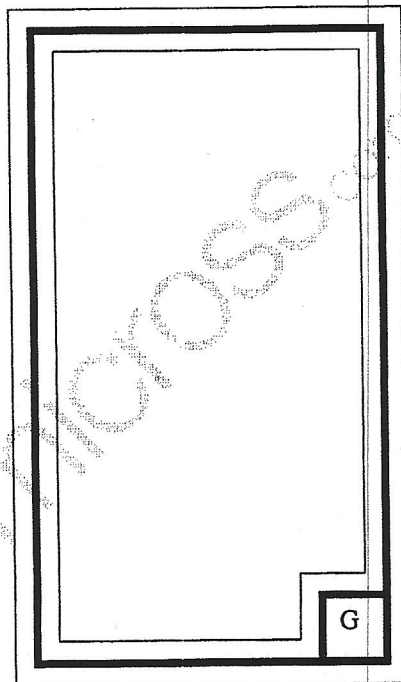
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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

HEX-0.9: 0020V-0040V, P-CHANNEL, GEN 12.1

PAD FUNCTIONS



G = GATE

Topside Metal: Aluminum
Backside Metal: TiNiAg
Backside Potential: Drain
Bond Pad Size: .004" min.
Mask Ref:

APPROVED BY: R Bacon

DIE SIZE : .056" X .101 "

DATE: 11/11/10

MFG: International Rectifier

THICKNESS: .007"

Part # IRFC9328